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(54) **CIRCUIT BOARD ASSEMBLY, CIRCUIT BOARD STACK STRUCTURE, AND ELECTRONIC DEVICE**

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**ABSTRACT**

A circuit board stack structure includes a third circuit board, a circuit board assembly, and a second circuit board that are stacked in sequence. The circuit board assembly includes a first connector, a first circuit board, and a second connection base that are stacked in sequence, where the first connector includes a second electrical connection portion and a second connection portion, and the second connection base includes a fourth connection portion; a first conducting wire on the first circuit board, the third connection portion, and the second connection portion are electrically connected in sequence, forming a second path between the first circuit board and the third circuit board; and the fourth connection portion, the fourth electrical connection portion, the third electrical connection portion, and the second electrical connection portion are electrically connected in sequence, forming a first path between the second circuit board and the third circuit board.

